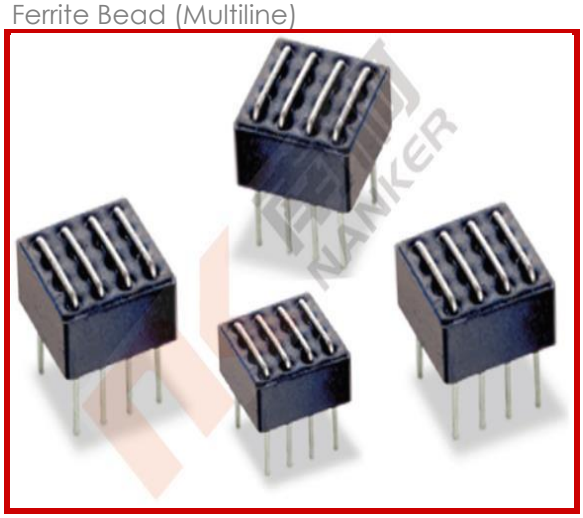
插件磁排
Ferrite Bead (Multiline)



特性
Characteristics

NiZn铁氧体磁芯的宽带滤波
Broadband filtering because of the NiZn-ferrite core

高阻抗共模电感，2x2绕组，由PCB线路连接制成
High impedance common mode inductor with 2x2 windings made by PCB line connection

一个组件中2、3或4线的射频共模电感器
RF common mode inductor for 2, 3 or 4 lines in one component

应用
Application

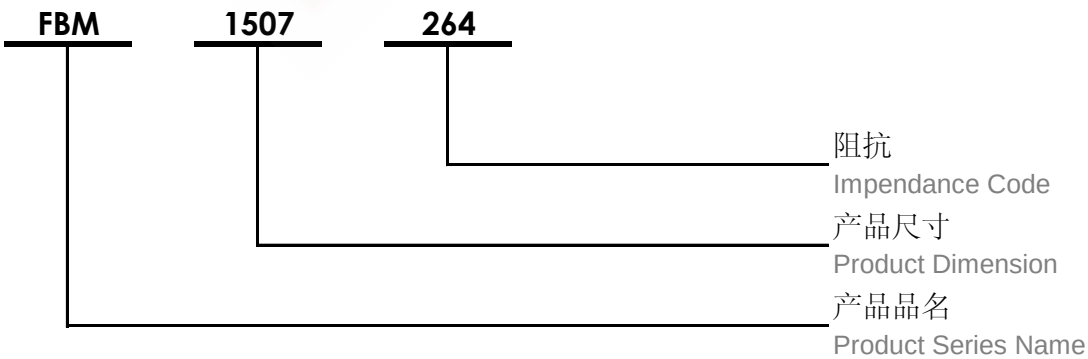
非常适合吸收EMC领域的共模或差模干扰
Perfect suitable for absorption of common or differential mode interferences in the field of EMC

多导体系统与电力电子
Multi-conductor systems and power electronics

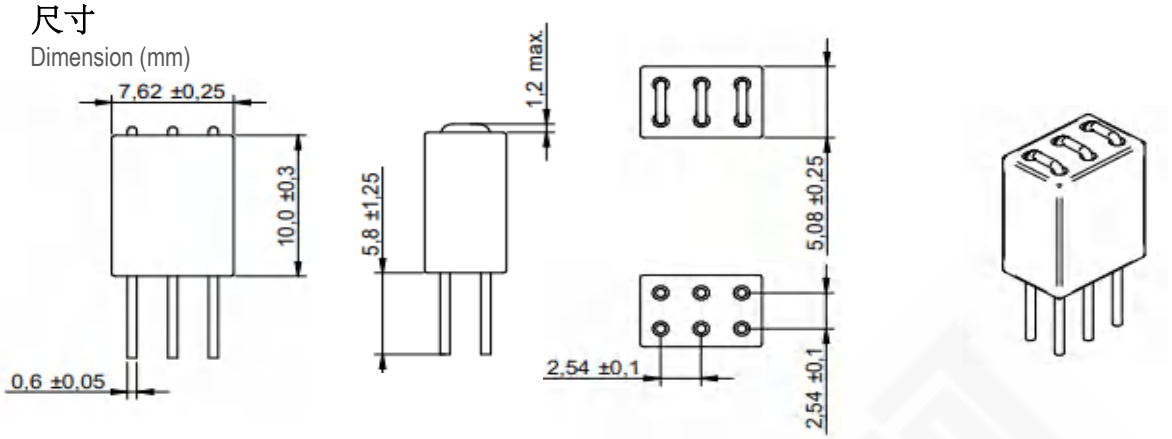
低压电源的滤波元件
Filtering components of low voltage power supplies

转动一圈，组件的性能就像信号的共模扼流圈的3倍或4倍
With one turn the component performes like a 3 or 4 times common mode choke for the signal

产品品名介绍
Product Number Structure



尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

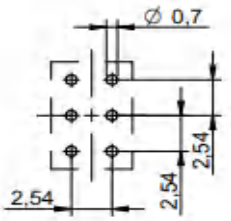
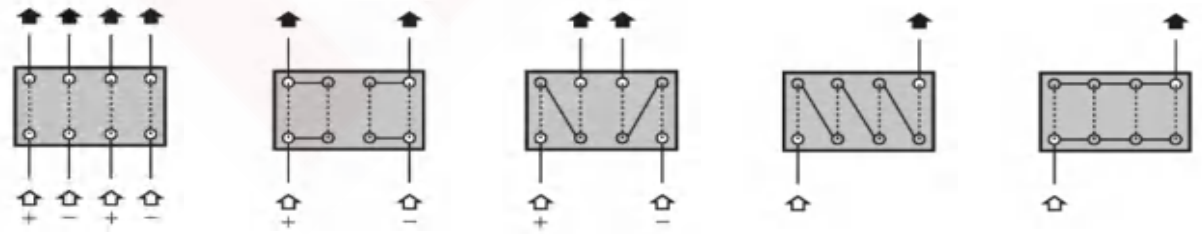


示意图
Schematics

电性特性
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	阻抗 Impedance Z (Ω) ±25%	固化温度 Curie Temperature Tc °C
FBM1507-264	@25MHz 212	@100MHz 264	140

布局示例
Layout Example



4x current compensated 4A Z~170... 350Ω @100MHz I=4A

2x current compensated 8A Z~170... 350Ω @100MHz I=8A

2x current compensated 4A Z~600... 900Ω @100MHz I=4A

4 turns 4A Z~900... 1500Ω @100MHz I=4A DCR<10mΩ

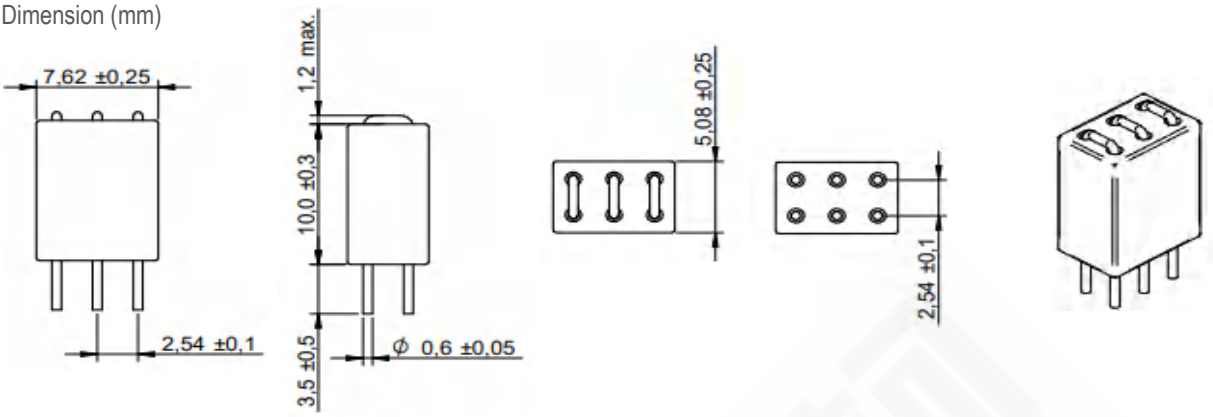
1 turns 16A Z~170... 350Ω @100MHz I=16A DCR<1mΩ

= PCB Layout ..... = Wire = IN = OUT

测试状态
Test Condition

☆ 工作温度：-25°C ~ +125°C
Operating Temperature: -25°C ~ +125°C

尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

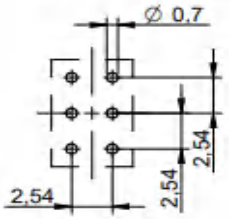
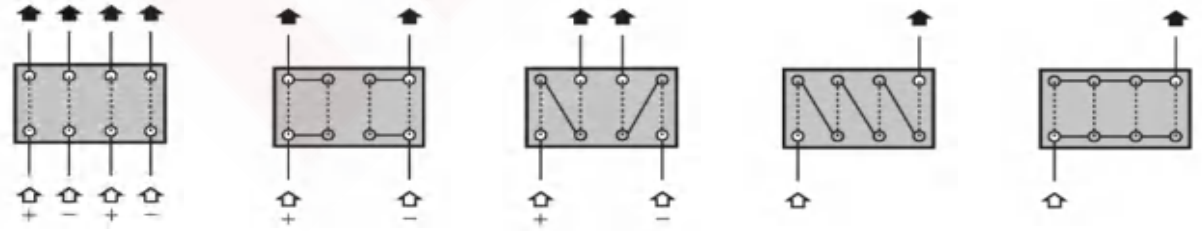


示意图
Schematics

电性特性
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	阻抗 Impedance Z (Ω) ±25%	固化温度 Curie Temperature Tc °C
FBM1307-264	@25MHz 212	@100MHz 264	140

布局示例
Layout Example



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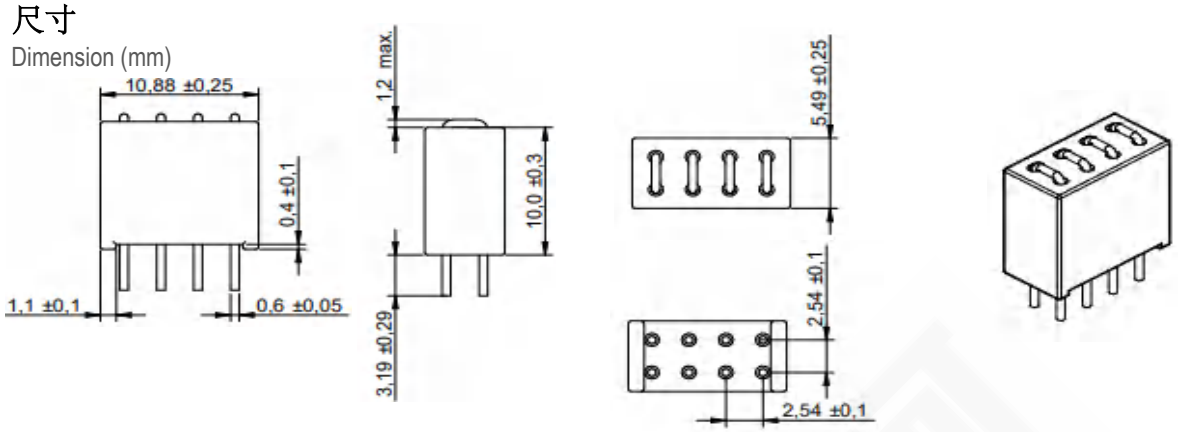
1 turns 16A Z~170... 350Ω @100MHz I=16A DCR<1mΩ

—○— = PCB Layout ..... = Wire ⇨ = IN ⇨ = OUT

测试状态
Test Condition

☆ 工作温度：-25°C ~ +125°C
Operating Temperature: -25°C ~ +125°C

尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

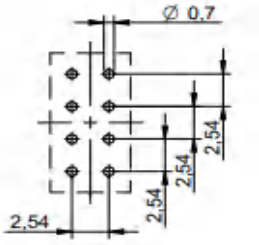
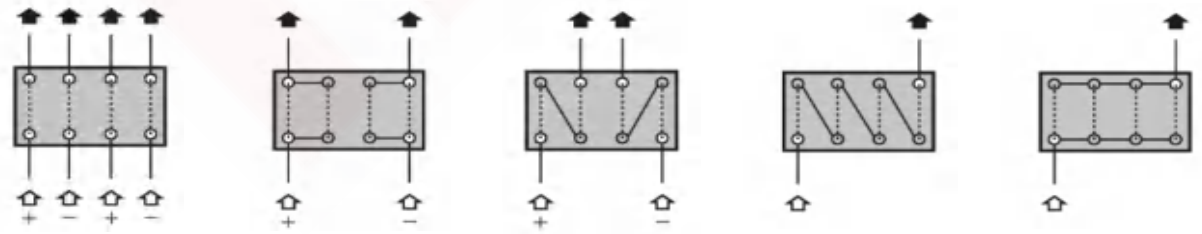


示意图
Schematics

电性特性
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	阻抗 Impedance Z (Ω) ±25%	固化温度 Curie Temperature Tc °C
FBM1410-249	@25MHz 209	@100MHz 249	140

布局示例
Layout Example



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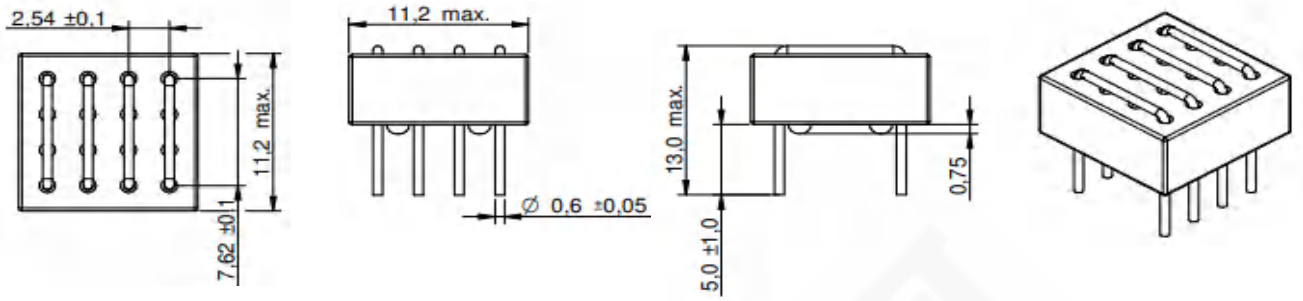
1 turns 16A Z~170... 350Ω @100MHz I=16A DCR<1mΩ

= PCB Layout ..... = Wire = IN = OUT

测试状态
Test Condition

☆ 工作温度：-25°C ~ +125°C
Operating Temperature: -25°C ~ +125°C

尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

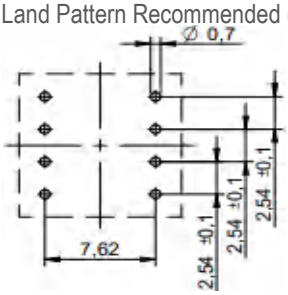
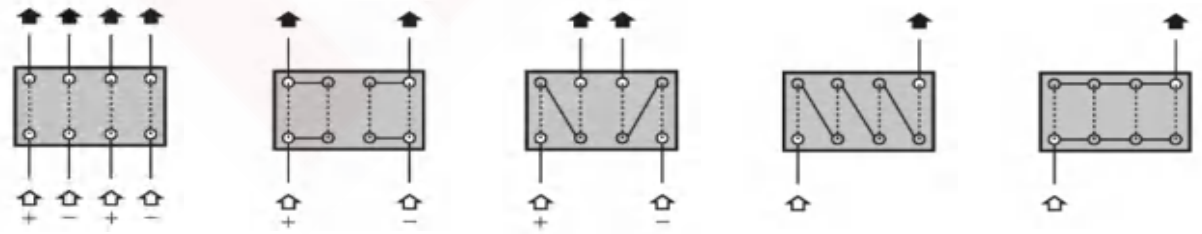


示意图
Schematics

电性特性
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	阻抗 Impedance Z (Ω) ±25%	固化温度 Curie Temperature Tc °C
FBM1311-170	@25MHz 136	@100MHz 170	140

布局示例
Layout Example



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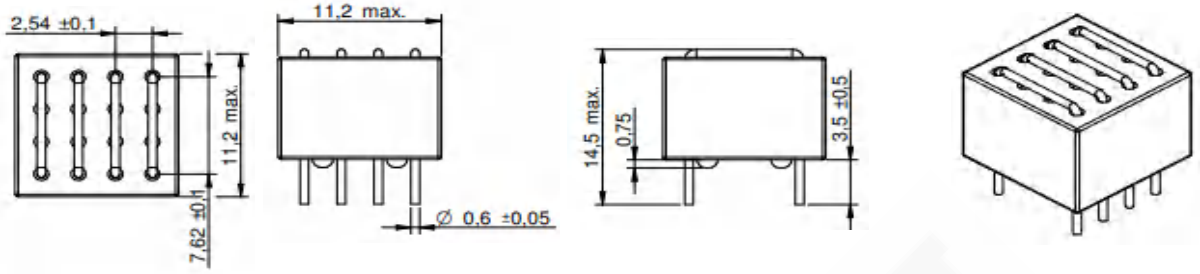
1 turns 16A Z~170... 350Ω @100MHz I=16A DCR<1mΩ

= PCB Layout ..... = Wire = IN = OUT

测试状态
Test Condition

☆ 工作温度：-25°C ~ +125°C
Operating Temperature: -25°C ~ +125°C

尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

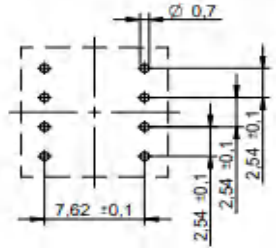
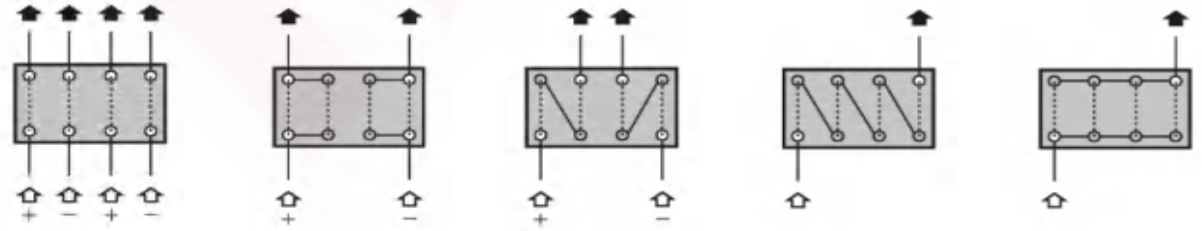


示意图
Schematics

电性特性
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	阻抗 Impedance Z (Ω) ±25%	固化温度 Curie Temperature Tc °C
FBM1411-248	@25MHz 208	@100MHz 248	140

布局示例
Layout Example



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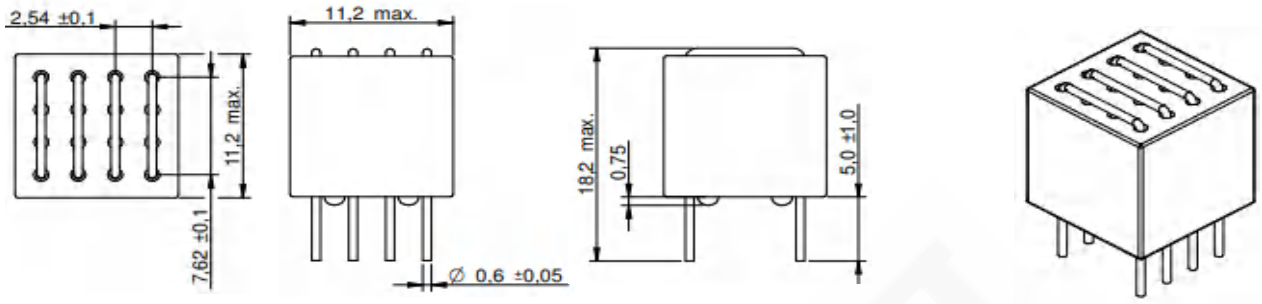
测试状态
Test Condition

☆ 工作温度：-25°C ~ +125°C
Operating Temperature: -25°C ~ +125°C

尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

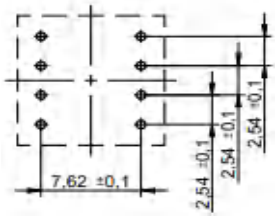
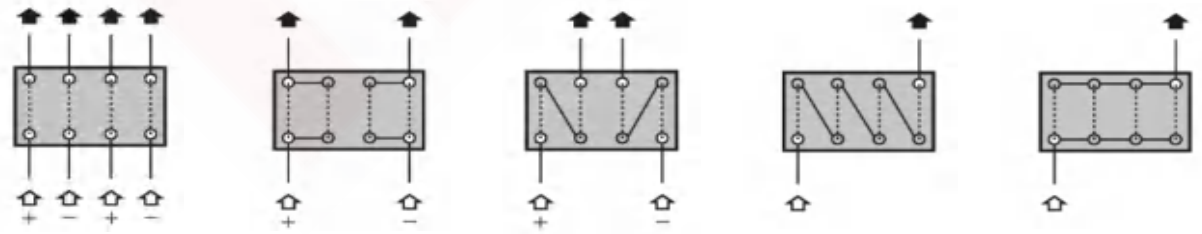


示意图
Schematics

电性特性
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	阻抗 Impedance Z (Ω) ±25%	固化温度 Curie Temperature Tc °C
FBM1811-334	@25MHz 292	@100MHz 334	140

布局示例
Layout Example



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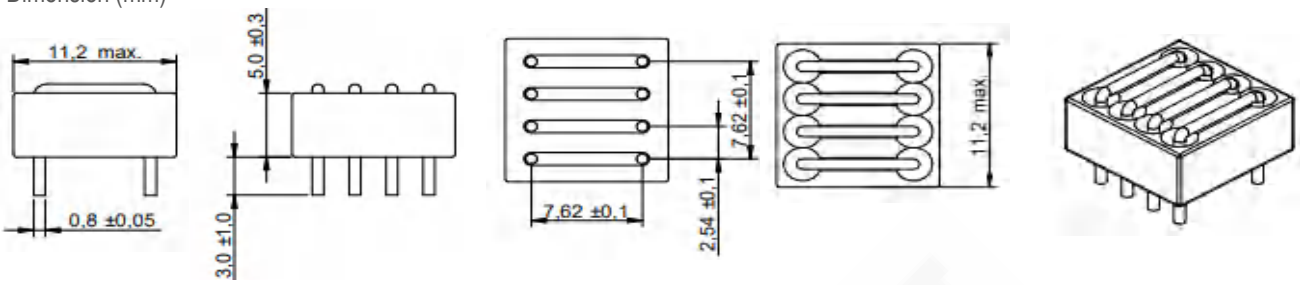
1 turns 16A Z~170... 350Ω @100MHz I=16A DCR<1mΩ

—○— = PCB Layout ..... = Wire ⇨ = IN ⇨ = OUT

测试状态
Test Condition

☆ 工作温度：-25°C ~ +125°C
Operating Temperature: -25°C ~ +125°C

尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

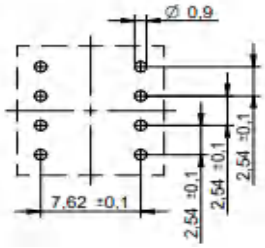
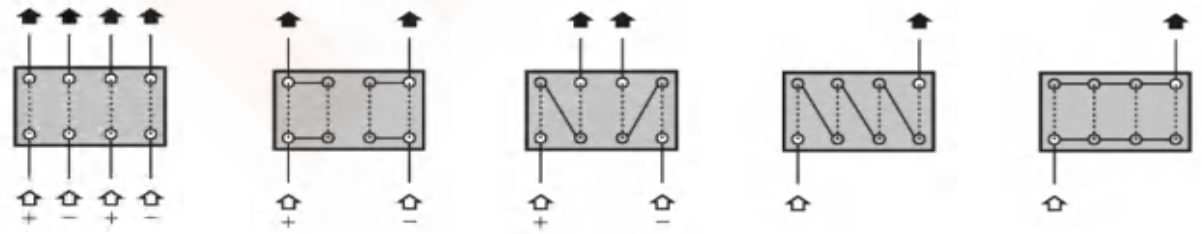


示意图
Schematics

电性特性
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	阻抗 Impedance Z (Ω) ±25%	固化温度 Curie Temperature Tc °C
FBM0811-150	@25MHz 115	@100MHz 150	140

布局示例
Layout Example



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4 turns 4A Z~900... 1500Ω @100MHz I=4A DCR<10mΩ

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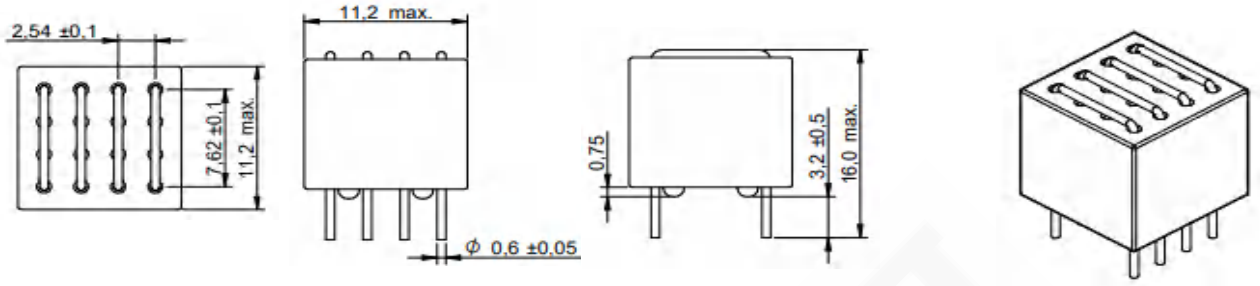
测试状态
Test Condition

☆ 工作温度：-25°C ~ +125°C
Operating Temperature: -25°C ~ +125°C

尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

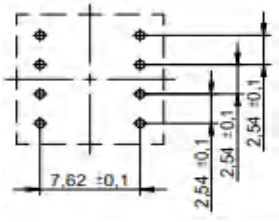
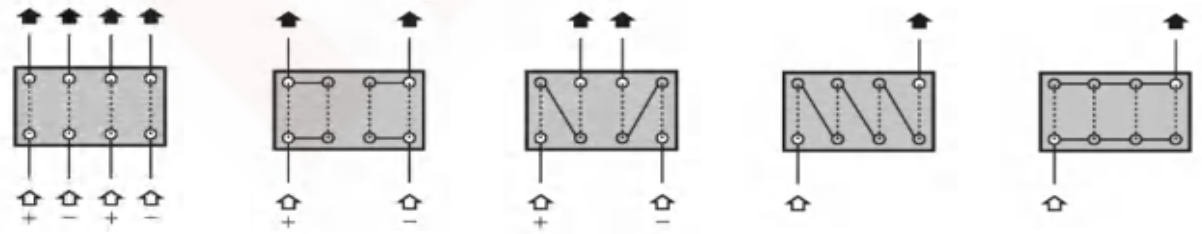


示意图
Schematics

电性特性
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	阻抗 Impedance Z (Ω) ±25%	固化温度 Curie Temperature Tc °C
FBM1611-334	@25MHz 292	@100MHz 334	140

布局示例
Layout Example



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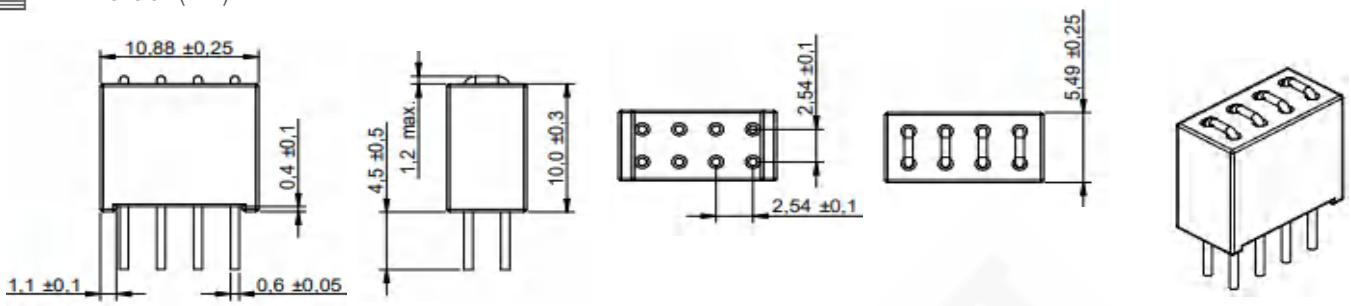
测试状态
Test Condition

☆ 工作温度：-25°C ~ +125°C
Operating Temperature: -25°C ~ +125°C

尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

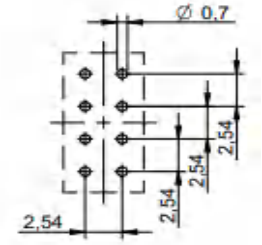
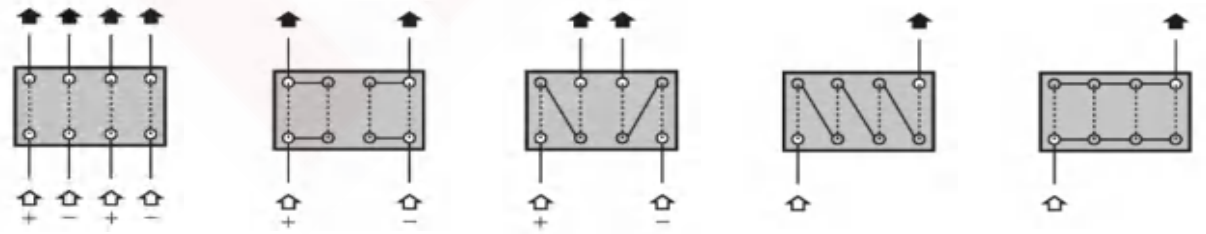


示意图
Schematics

电性特性
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	阻抗 Impedance Z (Ω) ±25%	固化温度 Curie Temperature Tc °C
FBM1510-249	@25MHz 209	@100MHz 249	140

布局示例
Layout Example



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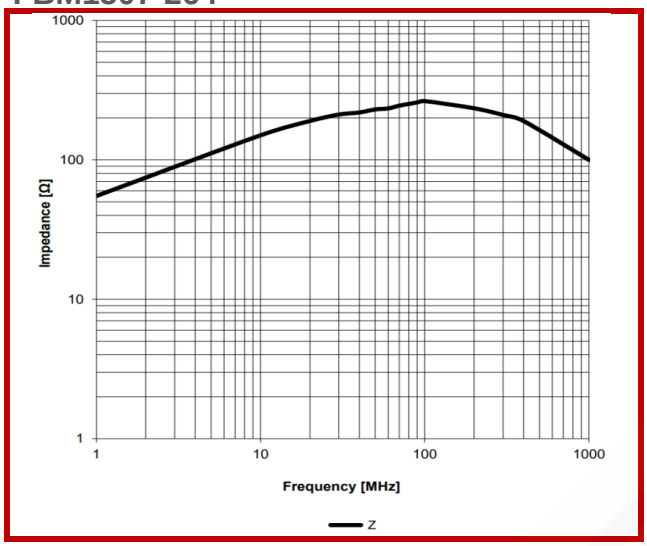
测试状态
Test Condition

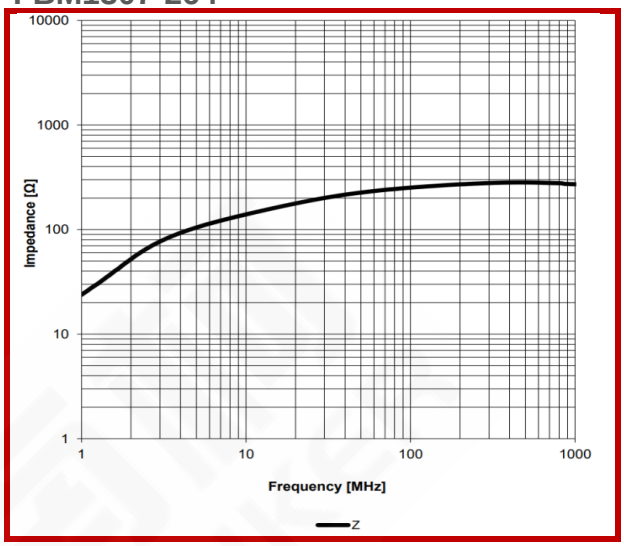
☆ 工作温度：-25°C ~ +125°C
Operating Temperature: -25°C ~ +125°C

典型阻抗特性
Typical Impedance Characteristics

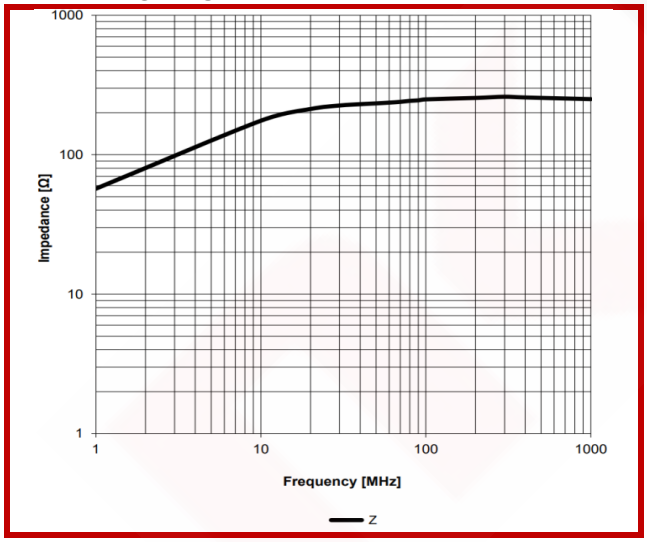
FBM1507-264



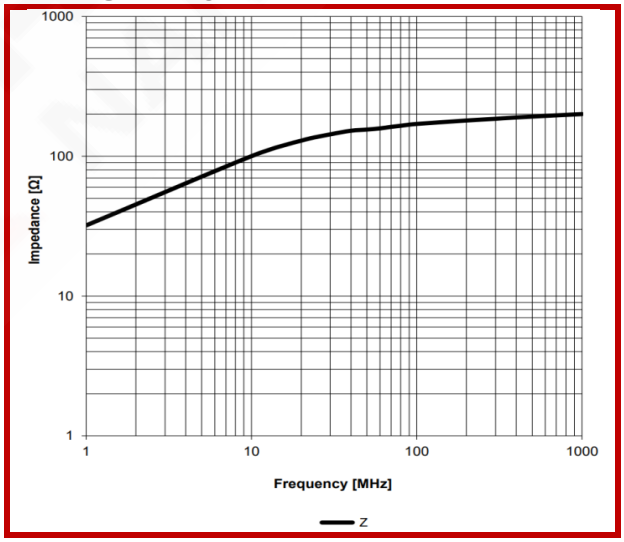
FBM1307-264



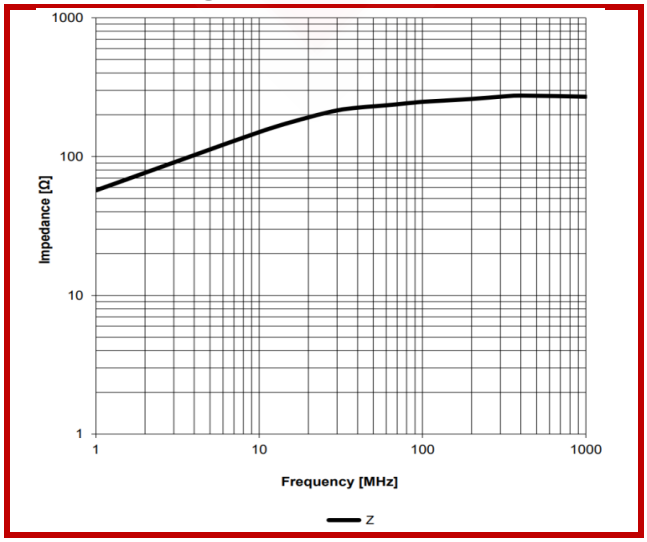
FBM1410-249



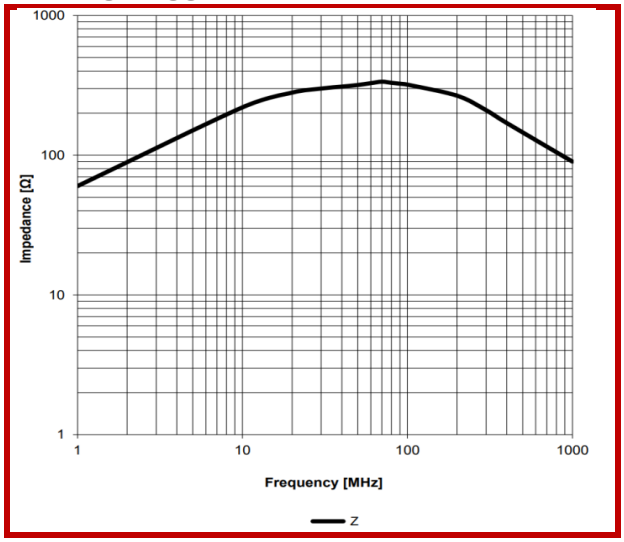
FBM1311-170



FBM1411-248

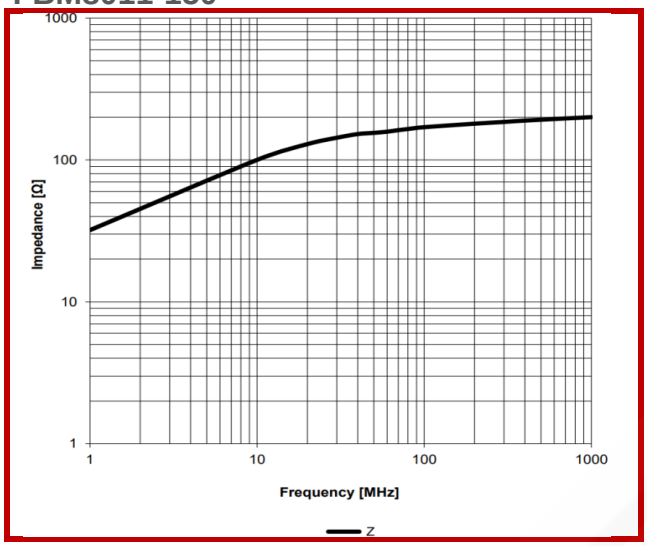


FBM1811-334

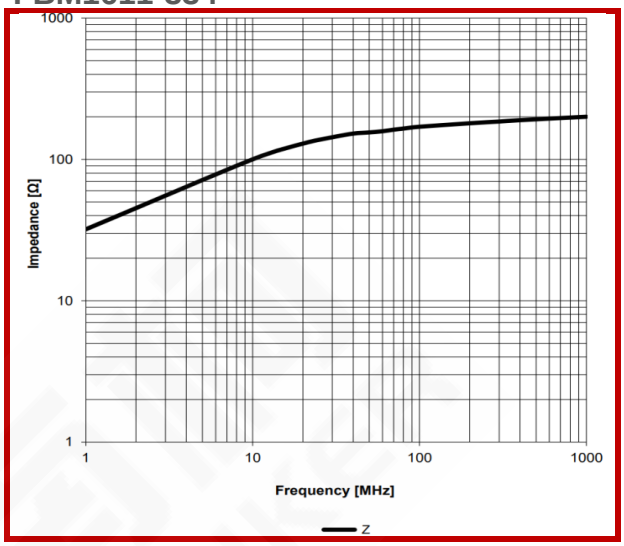


典型阻抗特性
Typical Impedance Characteristics

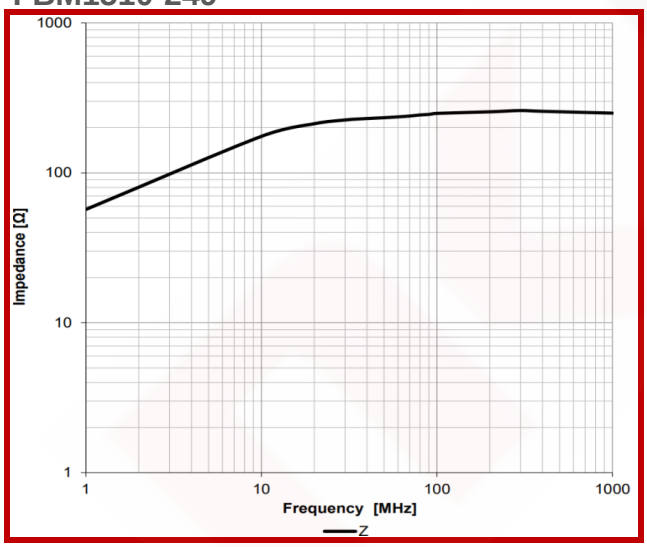
FBM8011-150



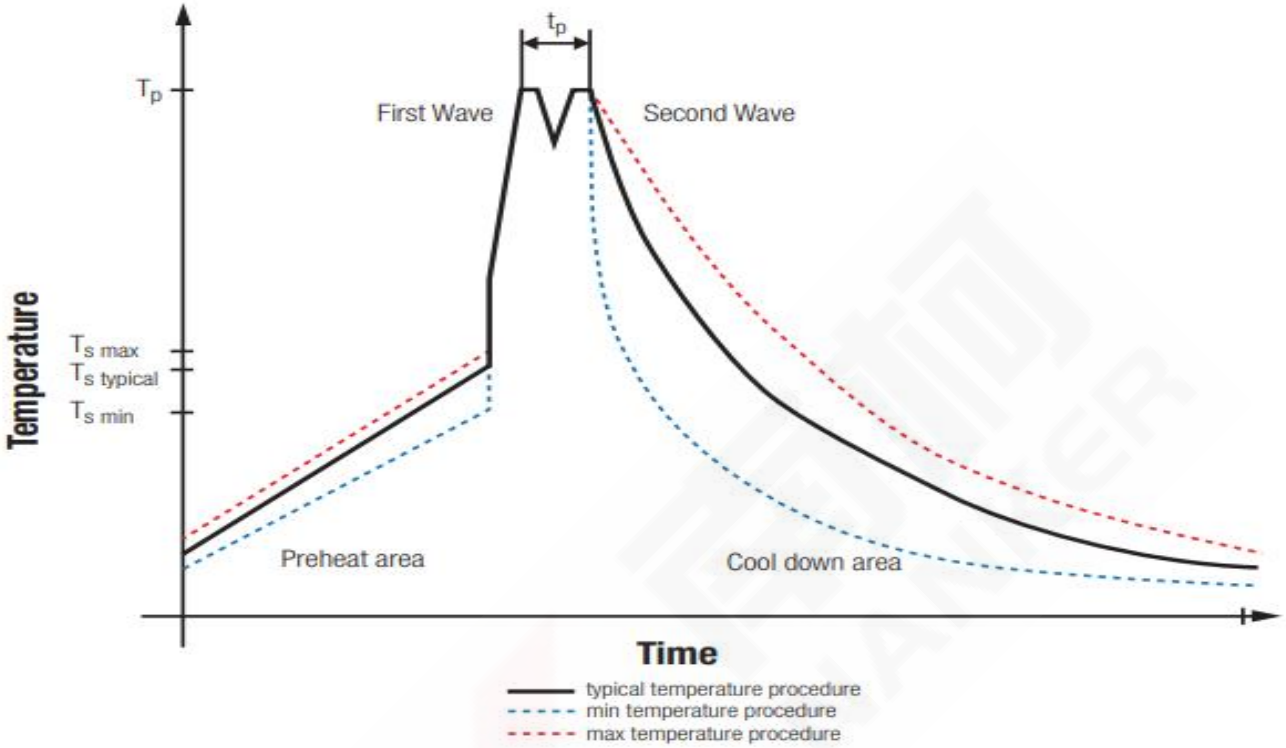
FBM1611-334



FBM1510-249



波峰焊线图
Classification Wave Soldering Profile



封装体峰值温度(Tp)分类
Classification Reflow Soldering Profile:

Profile Feature			Pb-Free Assembly	Sn-Pb Assembly
Preheat Temperature Min	$T_{s\ min}$	$T_{s\ min}$	100°C	100°C
Preheat Temperature Typical	$T_{s\ typical}$	$T_{s\ typical}$	120°C	120°C
Preheat Temperature Max	$T_{s\ max}$	$T_{s\ max}$	130°C	130°C
Preheat Time t_s from $T_{s\ min}$ to $T_{s\ max}$	t_s	t_s	70 seconds	70 seconds
Ramp-up Rate	Δ T	Δ T	150°C max	150°C max
Peak Temperature	T_p	T_p	250°C ~ 260°C	235°C ~ 260°C
Time of actual peak temperature	t_p	t_p	max. 10 seconds max. 5 seconds each wave	max. 10 seconds max. 5 seconds each wave
Ramp-down Rate, Min			~ 2K/seconds	~ 2K/seconds
Ramp-down Rate, Typical			~3.5K/seconds	~3.5K/seconds
Ramp-down Rate, Max			5K/seconds	5K/seconds
Time 25°C to 25°C			4 minutes	4 minutes

* 波峰焊参照标准EN61760-1:2006。
Wave Soldering is refer to standard EN61760-1:2006